L	Hits	Search Text	DB	Time stamp
Number .	16027	"microelectromechanical system" or MEMS	USPAT; EPC; JPO; IBM TDB	12403704728 CH:58
7	28	(wafer and magnets and hinges) and ("microelectromechanical system" or MEMS)	USFAT; EPG; JPO; IBM TDB	2003/04/28 08:59
8	284	(wafer or substrate) and magnets and hinges and etch\$3	USFAT; EPO; JPO; IBM TDB	2003/04/28
9	22	(wafer or substrate) and magnets and hinges and etch\$3 and gimbal	USFĀT; EPG; JPG; IBM TDB	2003/04/28 09:06
10	49	(wafer or substrate) and magnets and hinges and gimbal	USFAT; EP:; JPO; IBM TDB	2 153 104/28 09:27
11	150	(wafer or substrate) and magnets and hinges and etch $\$3$ and array	USFĀT; EP ; JPO; IBM TDB	2003/04/28 39:41
12	936	((216/22) or (216/24):.CCLS.	USFĀT; EP:; JPO; IBM TDB	2003:04/28 38:43
13	62	(((216/22) or (216/24)).CCLS.) and magnets	USPĀT; EP ; JPO; IBM TDB	2003/04,28 09:50
14	37	(((216/22) or (216/24)).CCLS.) and (hinges or gimbal)	USPĀT; EPO; JPO; IBM TDB	2000, 04, 28 09:40
15	10939	magnets same (wafers or substrate)	USFAT; EFO; JPO; IEM TDB	2003 04128 09:54
16	21	(((216/22) or (216/24)).CCLS.) and (magnets same (wafers or substrate))	USPAT; EFO; JFO; IBM TDB	2003/04/28
17	8	([(216/22) or (216/24)).CCLS.) and micromirror	USPĀT; EFO; JPO; IRM TDB	2008-04/28 10::1
18	48	(wafer or substrate) and magnets and micromirrors	USPĀT; EFD; JPD; IEM_TDB	2005/04/28 10:02